503674795 02/01/2016

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yi-Liang Ye	12/11/2015
Kuang-Hsiu Chen	12/11/2015
Chueh-Yang Liu	12/11/2015
Yu-Ren Wang	12/10/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15012821

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU **Address Line 1:** P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2658USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	02/01/2016

Total Attachments: 8

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PATENT REEL: 037638 FRAME: 0173

EPAS ID: PAT3721431

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PATENT REEL: 037638 FRAME: 0174

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

METHOD OF FABRICATING SEMICONDUCTOR STRUCTURE USING PLANARIZATION PROCESS AND CLEANING PROCESS

As the below named inventor, I here This declaration is directed to:	by declare that:					
☑ The attached application, or						
☐ United States application nu	mber		filed or	า	, 0	r
☐ PCT international application	number		filed	l on		
The above-identified application was	made or authorize	ed to be made b	by me.	***************************************		
I believe that I am the original invente application.	or or an original joi	int inventor of a	claimed	invention in	ı the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri	I false statement messionment of not me	nade in this decl ore than five (5)	laration i years, c	is punishabl er both.	е	
In consideration of the payment by	UNITED MICRO	DELECTRON	ICS	having a po	stal addres	s of
No.3, Li-Hsin Road 2, Science	-Based Industr	ial Park, Hsir	n-Chu (City 300, ⁻	Taiwan, R	l.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	l of the sum of Or d valuable conside	ne Dollar (\$ 1.00 eration.	0), the re	eceipt of wh	ich is hereb	ıy
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	id to any and all in tion and, in and to, any continuations	nprovements wh , all Letters Pate , continuation-in	nich are e ent to be n-part, di	disclosed in obtained fo visions, ren	the r said ewals	
I hereby covenant that no assignmen entered into which would conflict with	t, sale, agreement this assignment;	t or encumbranc	ce has b	een or will b	e made or	
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Lette stify as to the same	ers Patent and le e in anv interfer	egal equ ence. liti	ivalents as	mav be	
representatives any and all papers, ir maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said inven cessary or desirab	ition and said Le	etters Pa	itent and sa ses thereof	id : (Date of si	gning)
Note: An application data sheet (PTC inventive entity, must accompany this	0/SB/14 or equivale s form. Use this for	ent), including nomer manager metalong nomer metalong metalong nomer metalong nom	aming th	ne entire ventor.		

Page 1 of 8

F#NPO-P0002E-US1201

REEL: 037638 FRAME: 0175

LEGAL NAM	ME OF INVENTOR(AS	SIGNOR)		
Inventor:	Yi-Liang Ye		Date:	W15/12/11
Signature:	Yi-Liang	Te	***************************************	

Page 2 of 8

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☑ The attached application, or			
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The above-identified application was	made or authorized to be made b	by me.	***************************************
I believe that I am the original invento application.	or or an original joint inventor of a	claimed invention in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impris	false statement made in this decl sonment of not more than five (5)	aration is punishable years, or both.	
	UNITED MICROELECTRON CORP.	ICS having a postal add	ress of
No.3, Li-Hsin Road 2, Science-	Based Industrial Park, Hsir	n-Chu City 300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good and	I of the sum of One Dollar (\$ 1.00 I valuable consideration.)), the receipt of which is he	eby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applicati invention by the above application or substitutes, or extensions thereof, and	d to any and all improvements wh on and, in and to, all Letters Pate any continuations, continuation-in	ich are disclosed in the nt to be obtained for said	ΞE
I hereby covenant that no assignment entered into which would conflict with	, sale, agreement or encumbrand this assignment;	e has been or will be made	or
I further covenant that ASSIGNEE wil and documents relating to said invent known and accessible to I and will tes related thereto and will promptly exec	ion and said Letters Patent and le tify as to the same in any interfere	egal equivalents as may be	S
representatives any and all papers, in maintain, issue and enforce said appli equivalents thereof which may be neo IN WINTNESS WHEREOF, I have he	cation, said invention and said Le essary or desirable to carry out th	etters Patent and said ne proposes thereof.	signing)
Note: An application data sheet (PTO, inventive entity, must accompany this	/SB/14 or equivalent), including na form. Use this form for <u>each addi</u>	aming the entire tional inventor.	

NPO#NAU-P2658-USA:0 CUST#UMCD-2015-0682 Page 3 of 8

LEGAL NA	WIE OF HAVENTON(ASSIGNON)			
Inventor:	Kuang-Hsiu Chen	Date:	DEC 1 1 2015	
Signature:	Zuang - Hain Chen	***************************************		

Page 4 of 8

NPO#NAU-P2658-USA:0 CUST#UMCD-2015-0682

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good and	of the sum of One Dollar (\$ 1.0		
I hereby sell, assign and transfer to AS the entire right, title and interest in and invention as above-identified application invention by the above application or a substitutes, or extensions thereof, and	l to any and all improvements wi on and, in and to, all Letters Pate any continuations, continuation-i	hich are disclosed in the ent to be obtained for said n-part, divisions, repewals	EE
I hereby covenant that no assignment, entered into which would conflict with t	sale, agreement or encumbrandhis assignment;	ce has been or will be made	or
I further covenant that ASSIGNEE will and documents relating to said inventi- known and accessible to I and will test related thereto and will promptly exect	on and said Letters Patent and le ifv as to the same in any interfer	egal equivalents as may be	ts
representatives any and all papers, ins maintain, issue and enforce said applic equivalents thereof which may be neco IN WINTNESS WHEREOF, I have her	cation, said invention and said Le essary or desirable to carry out t	etters Patent and said he proposes thereof.	f signing)
Note: An application data sheet (PTO/sinventive entity, must accompany this t	SB/14 or equivalent), including n form. Use this form for <u>each add</u>	aming the entire itional inventor.	

Page 5 of 8

LEGAL NAI	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Chueh-Yang Liu	Date:	2015/12/11	
Signature:	Chueh- Yang Lin			

Page 6 of 8

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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The above-identified application number The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both. In consideration of the payment by UNITED MICROELECTRONICS having a postal address or CORP. No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O. (referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration. I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment; I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the	☑ The attached application, or	,		
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LEGAL NA	WIE OF INVENTOR(ASSIGNOR)		
Inventor:	Yu-Ren Wang	Date:	2015/12/16
Signature:	Yu-Ren Wang		

Page 8 of 8

NPO#NAU-P2658-USA:0 CUST#UMCD-2015-0682

RECORDED: 02/01/2016

F#NPO-P0002E-US1201 DSB0-104U035915

PATENT REEL: 037638 FRAME: 0182